

# SMART SENSORS

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Jamia Millia Islamia, New Delhi

19<sup>th</sup> December, 2015

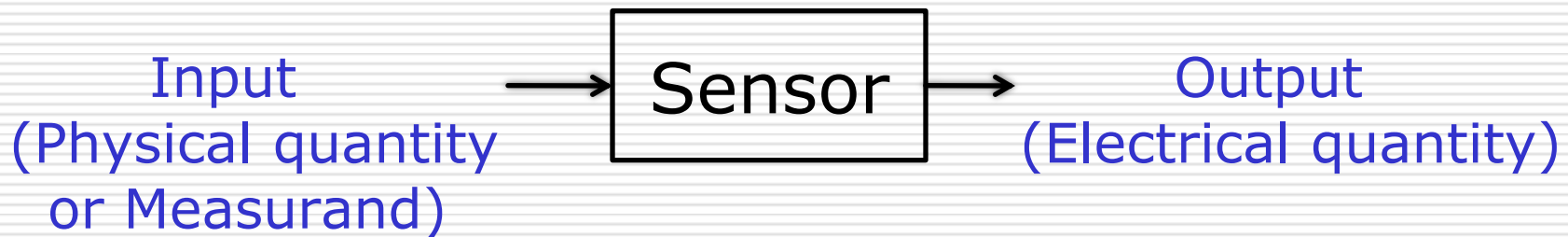
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# Smart-Sensor Basics

# What is a Sensor?

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- ❖ Device that senses a **physical quantity**
- ❖ This physical quantity becomes **input** to the sensor
- ❖ **Output** of the sensor is an electrical quantity
- ❖ Input is called measured quantity or “**measurand**”



# Sensor Input

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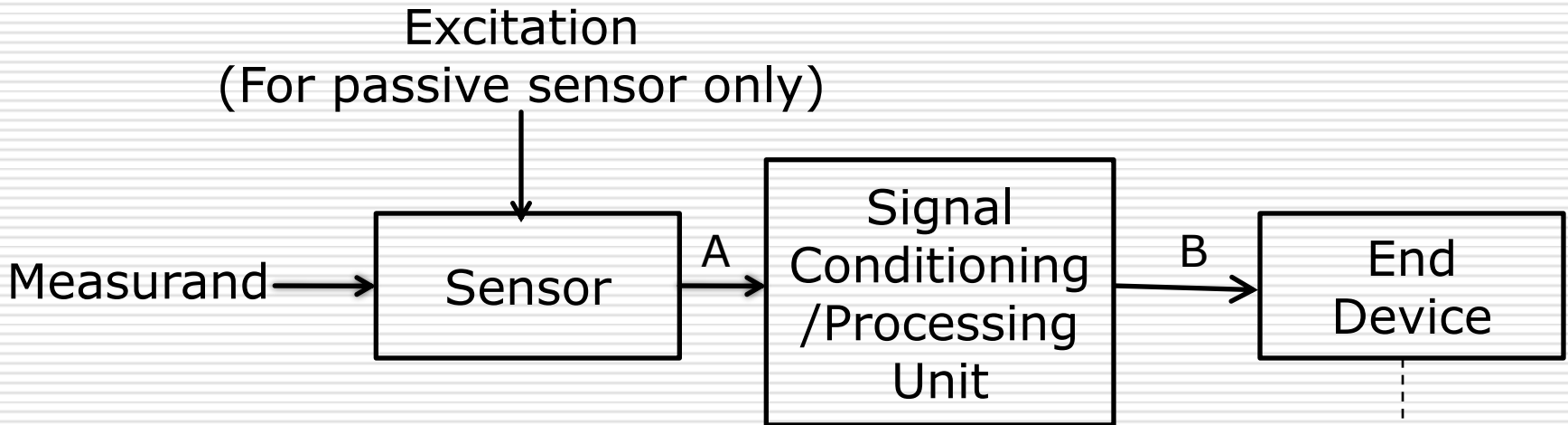
- ❖ Input to the sensor is the *sensed or measured quantity, called as **measurand***
- ❖ Examples of measurand are:
  - Temperature
  - Pressure and force
  - Torque
  - Displacement, velocity and acceleration
  - Flow, level and head
  - Humidity
  - Gas concentration
  - Voltage and current
  - Power and power factor

# Sensor Output

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- ❖ The electrical output of a sensor can be one of the two types:
  - ***Variation of an electrical parameter***
  - ***An electrical signal***
- ❖ Variation of electrical parameter means
  - Variation of resistance ( $\Delta R$ ), or
  - Variation of inductance ( $\Delta L$ ), or
  - Variation of capacitance ( $\Delta C$ )
- ❖ Electrical signal means
  - Voltage signal, or
  - Current signal

# Sensor-Based Measurement System



Conditions or processes electrical signal A into signal B to make it compatible with End Device, both in form and magnitude.

- Indicating device
- Display device
- Storage device
- Comm. device
- Data processor

# Analog Electronic Circuits used for Signal Conditioning

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## □ Amplifiers

- D.C. coupled
- A.C. coupled
- Differential
- Instrumentation

## □ Operational circuits

- Adder
- Subtractor
- Multiplier
- Divider
- Integrator
- Differentiator

## □ Active filters

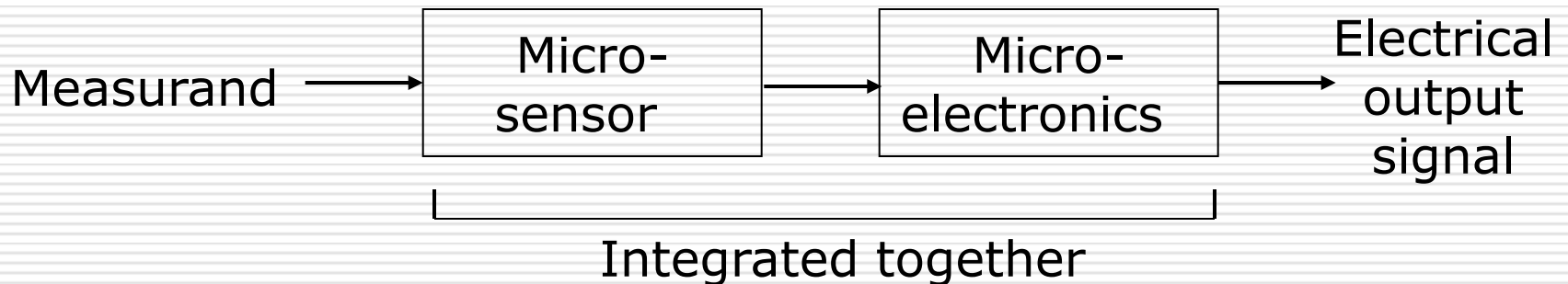
- Low pass
- High pass
- Band pass
- Band reject (notch)

## □ Modulators/Demodulators

- Pulse width modulator (PWM)
- Amplitude detector
- Phase sensitive amplitude detector

# What is a Smart Sensor?

- Most of the sensors now ***labeled as Smart Sensors*** by their manufacturers and ***accepted as Smart Sensors*** by users would fit into the following definition.
- *“Smart Sensor is a micro-sensor suitably integrated with appropriate micro-electronics, such that the final output is fully or easily compatible with the intended end device or devices”.*





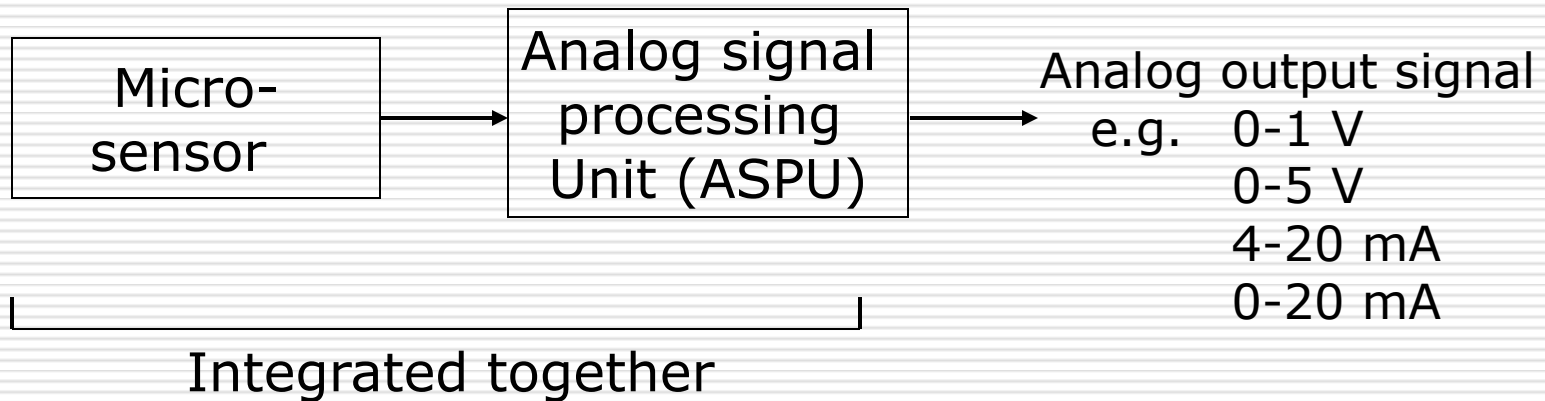
# Levels of Integration

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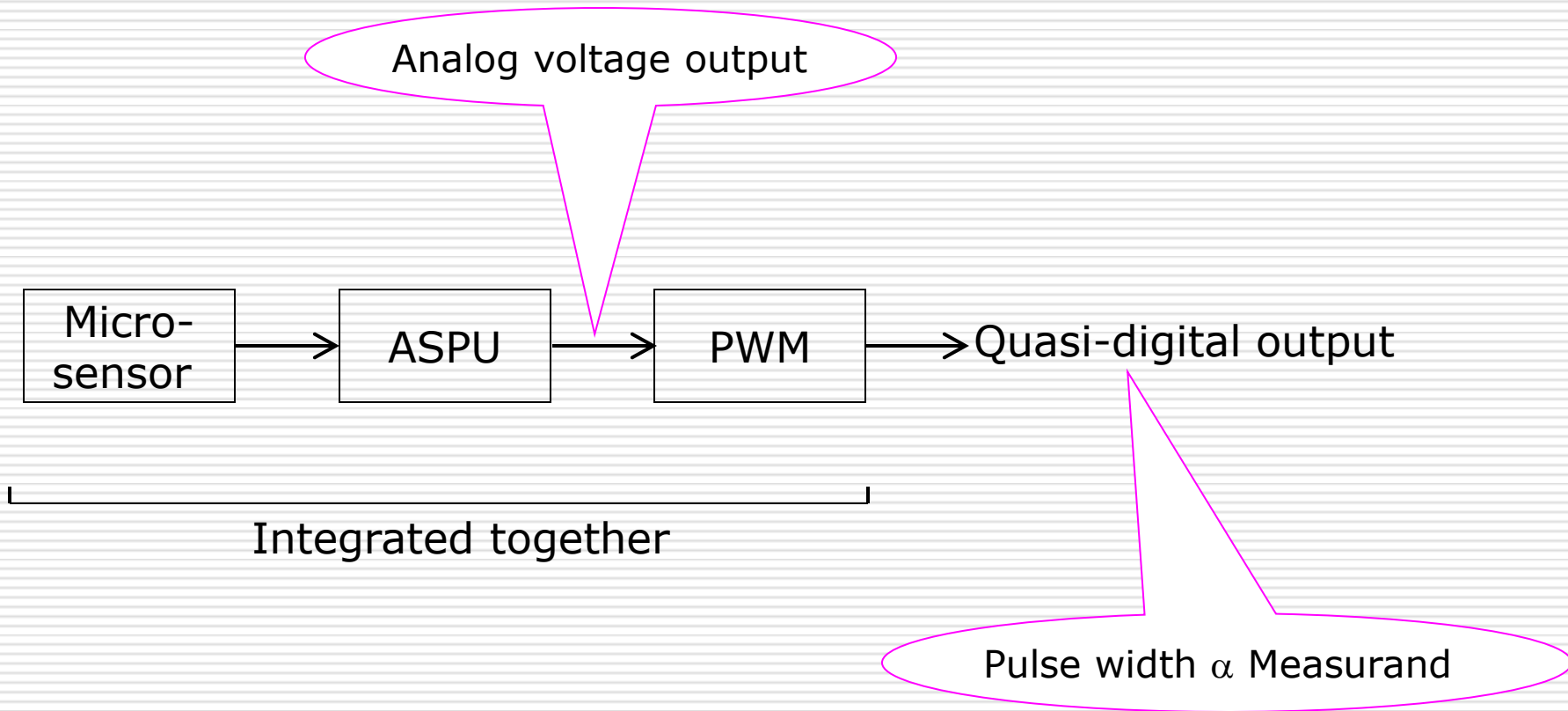
- ❖ The output signal of smart sensor can have one of three forms:
  - Analog
  - Digital
  - Quasi-digital (PWM or pulse frequency)
  
- ❖ Extent/ level of integration of electronics with the micro-sensor:
  - Lowest Level: Smart sensor with analog output
  - Low Level: Smart sensor with quasi-digital output
  - High Level: Smart sensor with digital output
  - Higher Level: Smart intelligent sensor
  - Highest Level: Smart network sensor

# Smart Sensor with Analog Output

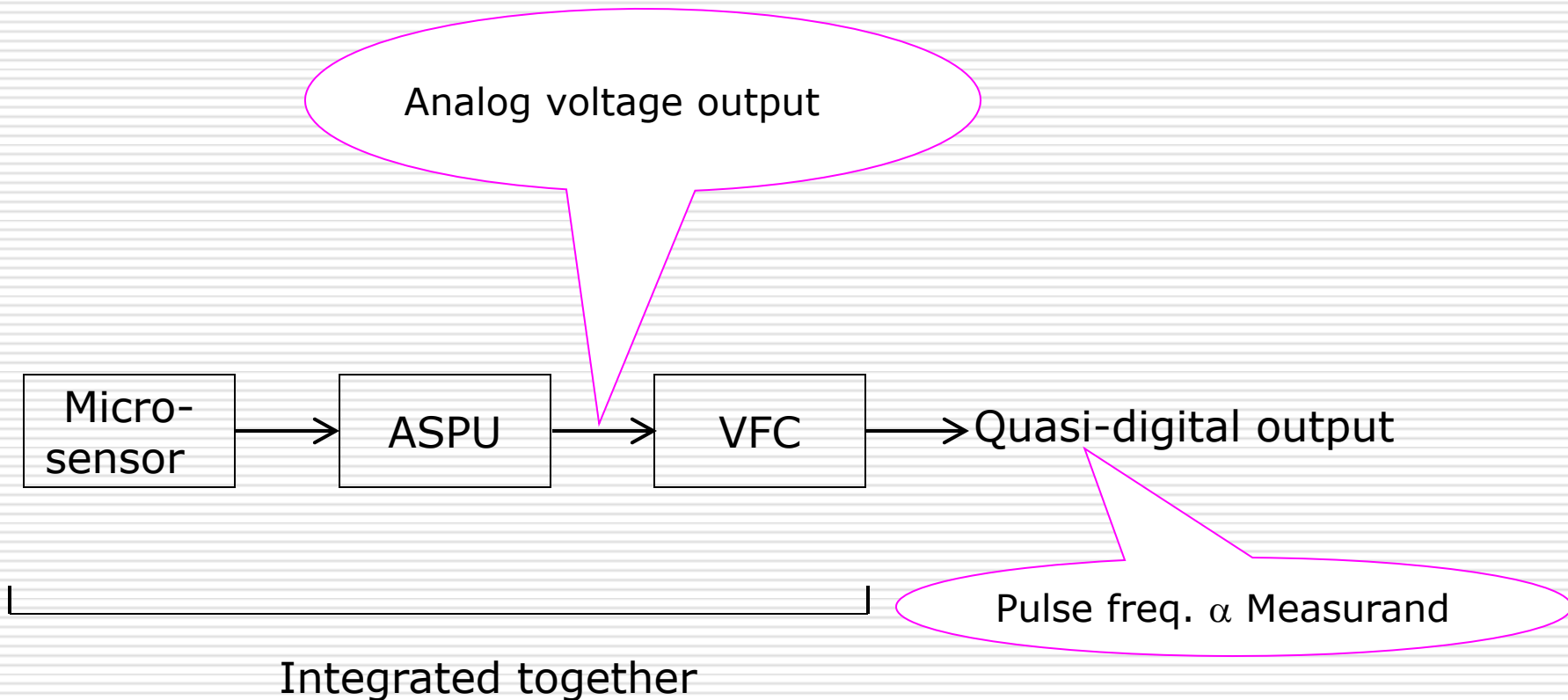
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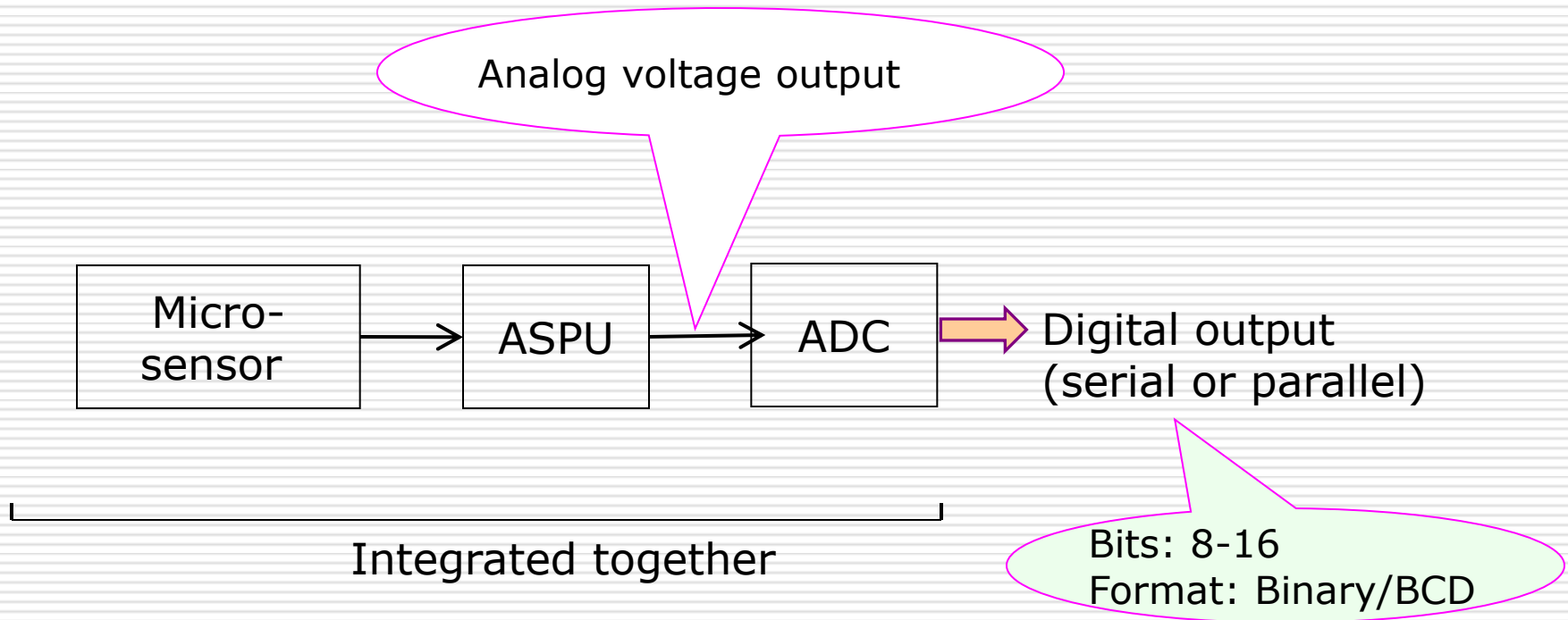
# Smart Sensor with PWM Output



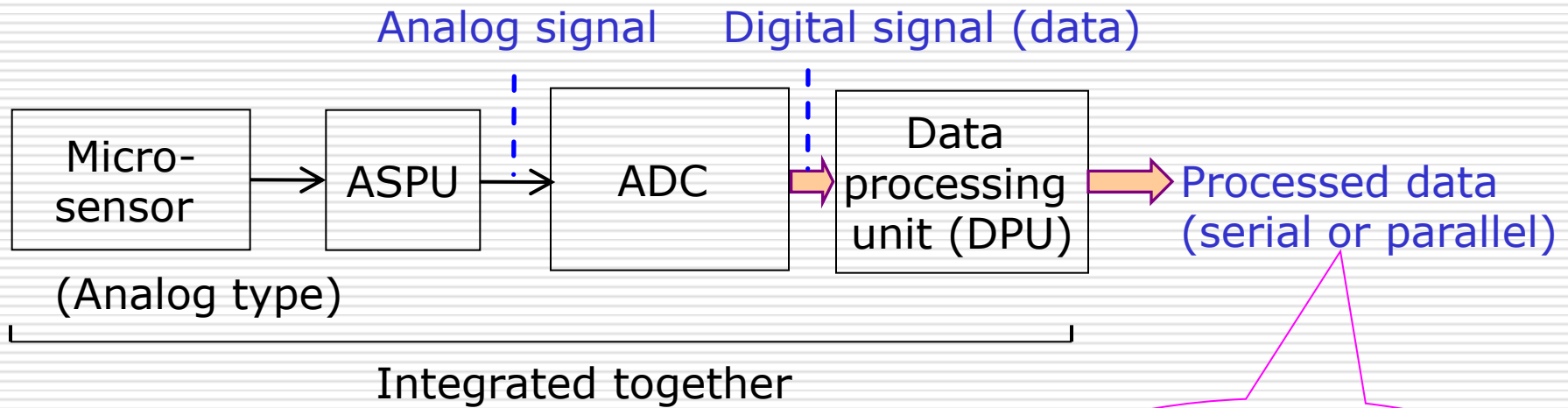
# Smart Sensor with Pulse-Frequency Output



# Smart Sensor with Digital Output



# Intelligent Sensor



DPU = Microcontroller

OR

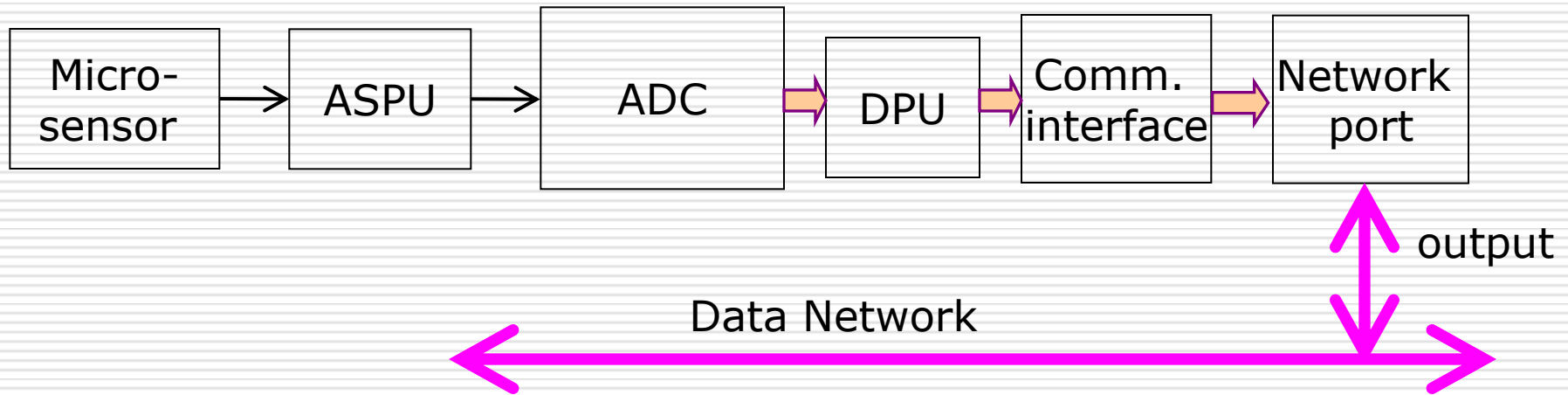
$\mu$ P + memory + I/O interface

OR

DSP + memory + I/O interface

Can be readily connected to a host computer or other digital system

# Network Sensor



***Output:*** processed data on integrated network port in appropriate format

# Advantages of Smart Sensor (1)

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## 1. User's Convenience because of:

- No wiring
- Compact size
- No headache of selecting SC
- No headache of designing SC

## 2. Superior Performance because:

- Externally-induced noise absent, high SNR
- Built-in sensor-specific SC circuits perform better
- Built-in negative feedback reduces nonlinearity
- Built-in compensating circuits reduce sensitivity to temperature/ excitation changes



# Advantages of Smart Sensor (2)

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## 3. High Reliability because of:

- Reduced component count
- Reduced wiring

## 4. Cost Reduction because of:

- Concurrent production of electronics and sensor
- Mass production techniques

# Additional Advantages of Integrating DPU

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- ❑ Performance Improvement because of:
  - Linearization of response using software
  - Reduction of cross-sensitivity using software
  - Automatic self calibration
- ❑ Simpler Interfacing because:
  - Data formatting can be done as per need
- ❑ Internal Data Logging
  - On-chip EEPROM or flash-RAM
  - Storage of field-measurement data
- ❑ Higher flexibility

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# Smart-Sensor Technologies

# Smart Sensor Technologies

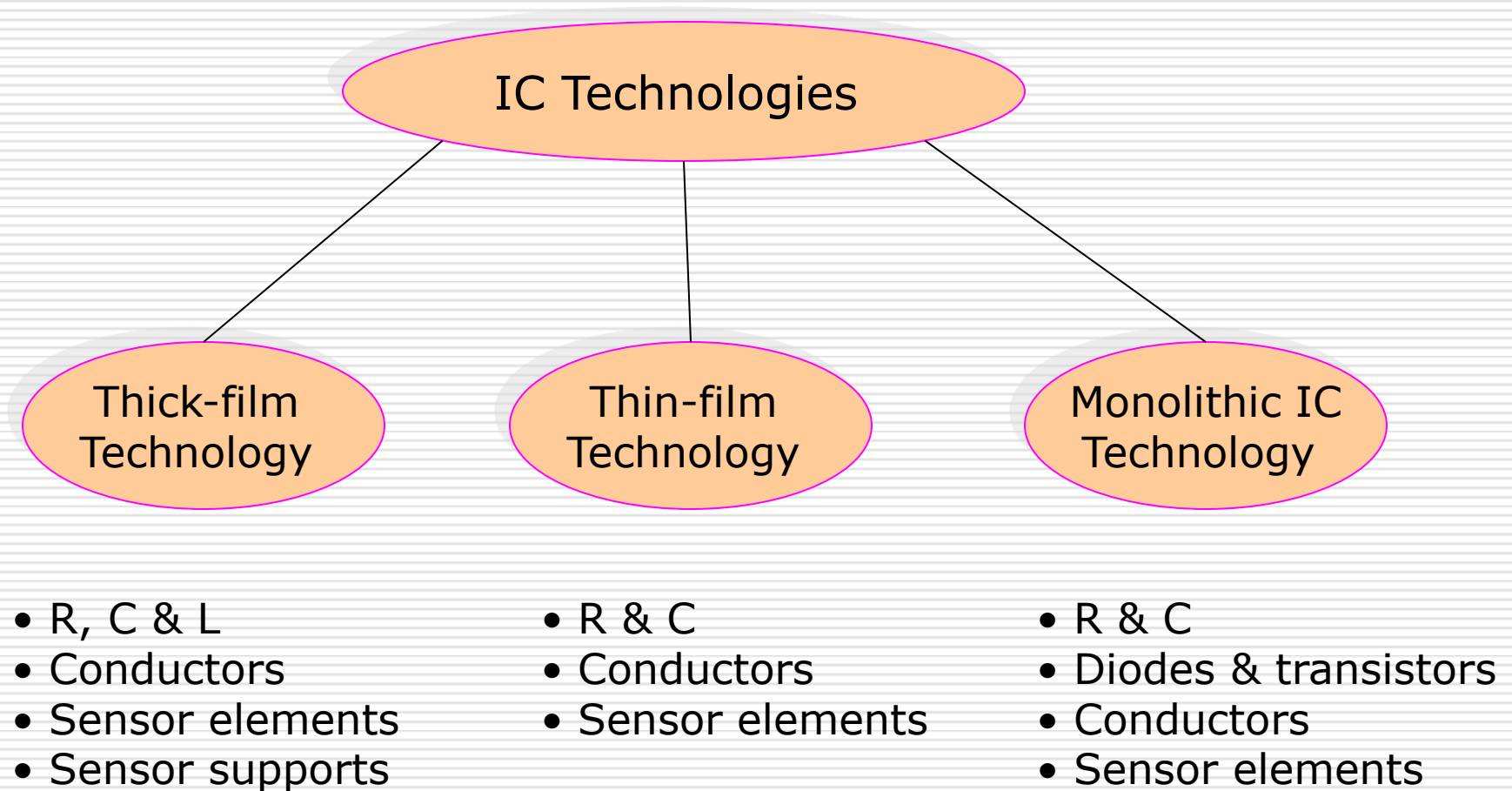
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Two types of technologies used:

- ❑ IC Technologies
- ❑ Micromachining Technologies

# IC Technologies & Capabilities

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# Thick-Film Sensor Elements

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- ❑ Temperature Sensors: Film RTD
  - Film thermistor
  - Film thermocouple
  
- ❑ Pressure Sensors: Film diaphragms
  - Film capacitors
  - Piezo-electric pastes
  - Piezo-resistive pastes
  
- ❑ Light Sensors: Photo-conductive pastes
  
- ❑ Magnetic Sensors: Magneto-resistive pastes
  
- ❑ Humidity Sensors: Organic polymer based pastes
  
- ❑ Gas Sensors: Metal-oxide pastes

# Advantages of Thick Film Technology

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- ❑ Components can withstand high temperatures
- ❑ Large voltage / current excitation can be used
- ❑ Heaters can be integrated
- ❑ Economical for low-volume production

# Thin-Film Deposition Techniques

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- Sputtering or cathodic deposition
- Vacuum evaporation
- Spin casting
- Reactive growth
- Chemical vapour deposition
- Plasma deposition



# Thin-Film Materials

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- ❑ For conductors: Aluminium or gold
- ❑ For resistors: Nichrome
- ❑ For dielectrics: Silicon dioxide
- ❑ For sensors (examples)
  - Strain gauge: Nichrome, polycrystalline silicon
  - RTD: Platinum
  - Gas sensor: Zinc oxide
  - Piezo-resistive pressure sensor: Nichrome, polycrystalline silicon
  - Thermo-anemometric flow sensor: Gold

# Advantages of Thin-Film Technology

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- ❑ Almost any metal can be deposited to produce thin-film sensors
- ❑ Add resistances, capacitances and sensors to monolithic IC.
- ❑ Miniaturization (smaller dimensions than thick-film devices).
- ❑ Economical for high-volume production.

# Monolithic IC Technology: Advantages

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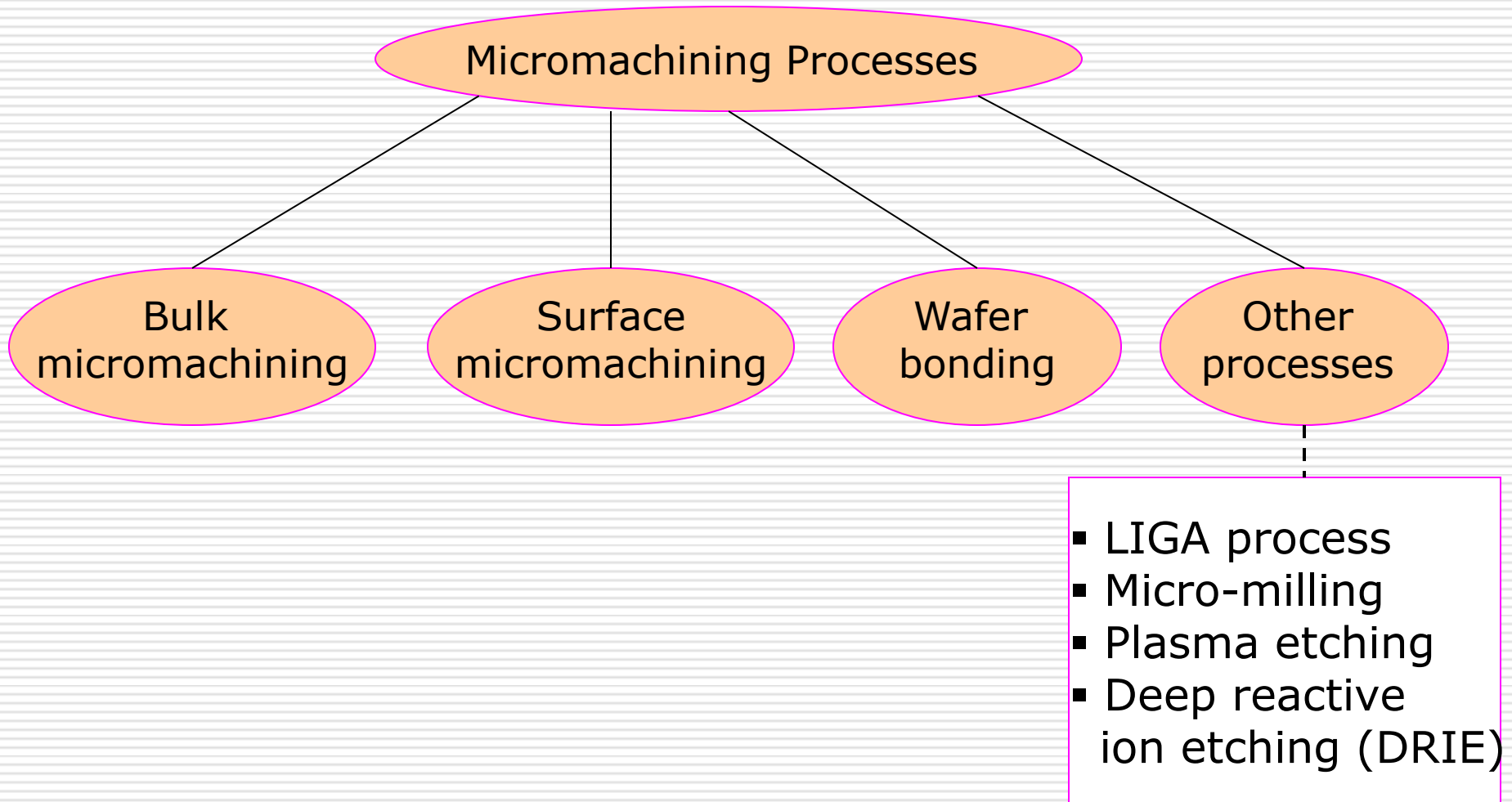
- Both active and passive devices
- Very high density of devices

# Monolithic IC Technology: Limitations

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- A few types of sensors only
- Resistances in medium-range only
- Capacitances of small values only

# Micromachining Technologies



# Bulk Micromachining

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- ❑ Si wafer is etched on both sides
- ❑ Etching done with masks and etchants
- ❑ Pattern defined by photo-lithographic technique
- ❑ Etching processes:
  - Isotropic etching
  - Anisotropic etching

# Isotropic Etching

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- ❑ Etchants used have same etching rate for all crystallographic orientations of silicon wafer (crystal)
  
- ❑ Common Etchants (examples)
  - Sulfur hexafluoride (SF<sub>6</sub>)
  - Hydrogen fluoride (HF)
  
- ❑ Structures Produced (examples)
  - Semi-spherical cavity
  - Rim-cantilever

# Anisotropic Etching

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- ❑ Etchants used have **different** etching rates for different crystallographic orientations of silicon wafer (crystal)
  
- ❑ Common Etchants (examples)
  - Ethylene-diamine pyrocatechol (EDP)
  - Potassium hydroxide (KOH)
  
- ❑ Structures Produced (example)
  - Diaphragm



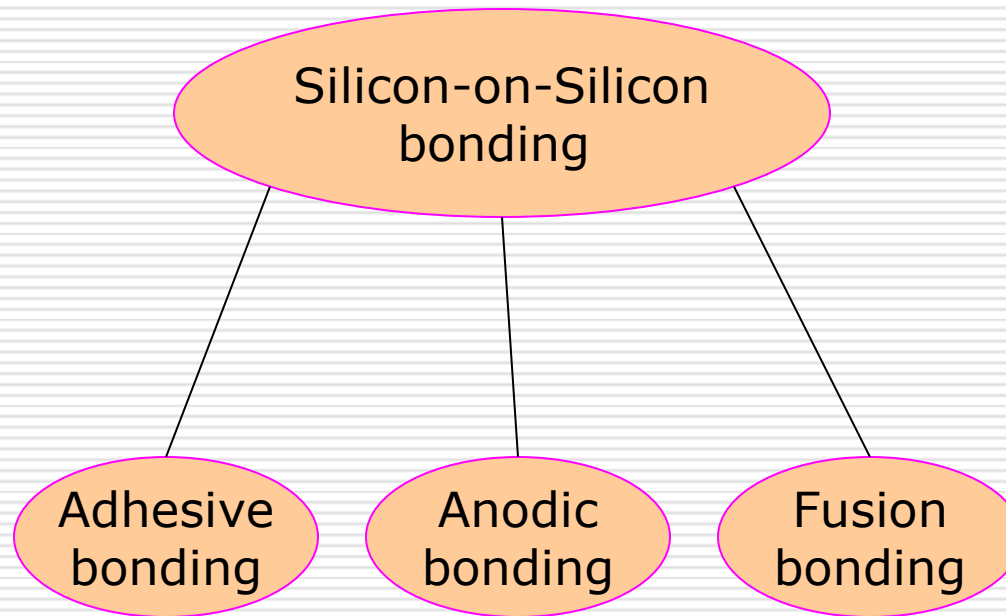
# Surface Micromachining

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- ❑ Etching and deposition processes from one surface
- ❑ 3-dimensional structure built by stacking layers
- ❑ Sacrificial and structural layers used
- ❑ Substrate is usually Si; glass also used
- ❑  $\text{SiO}_2$  and SiN for masking

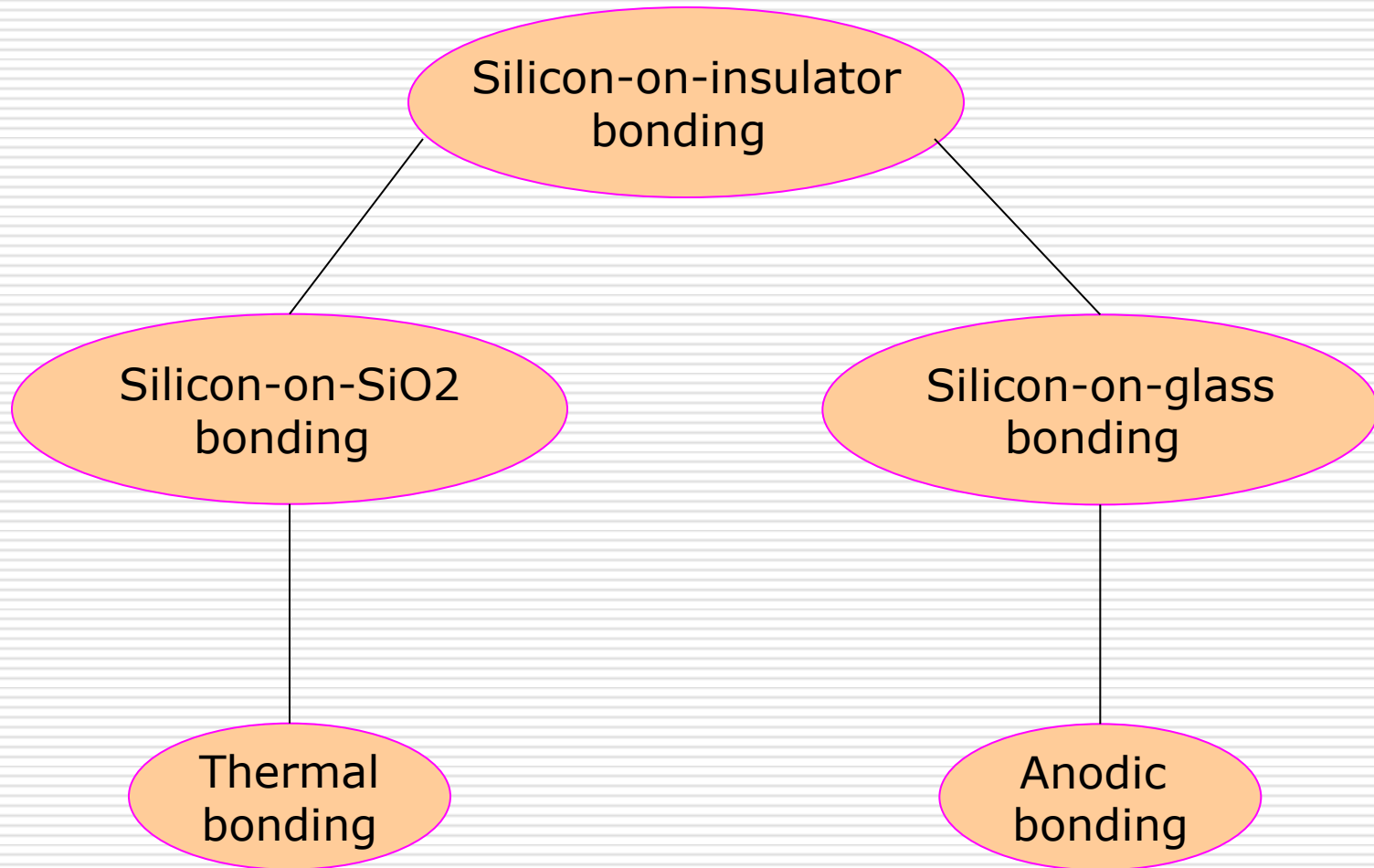
# Wafer Bonding (1)

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# Wafer Bonding (2)

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# Smart-Sensor Case Studies

# Case Study # 1

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**Smart Three-Terminal Temperature Sensor**  
**or**  
**Three-Terminal IC Temperature Sensor**  
**or**  
**Voltage-Output IC Temperature Sensor**

**LM35/LM34**

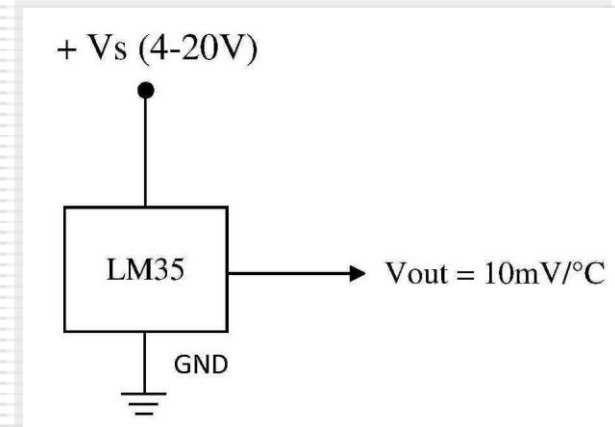
Manufacturer: National Semiconductor Corporation

Website: [www.national.com](http://www.national.com)

# Major Specifications

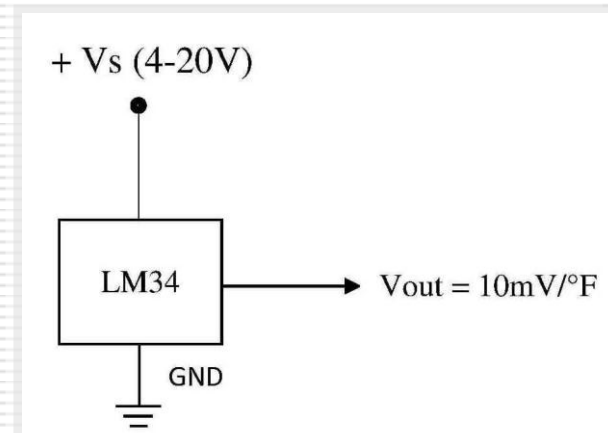
## □ LM35: Centigrade (or Celcius) Temperature Sensor

- Range: -55 to +150 °C
- Output (Sensitivity): 10 mV/°C
- Accuracy: ±0.2 °C (typical)
- Linearity: ±0.2 °C (typical)
- Current Drain: 65 μA (typical)



## □ LM34: Fahrenheit Temperature Sensor

- Range: -50 to + 300 °F
- Output (Sensitivity): 10 mV/°F
- Accuracy: ±0.4 °F (typical)
- Linearity: ±0.3 °F (typical)
- Current Drain: 75 μA (typical)



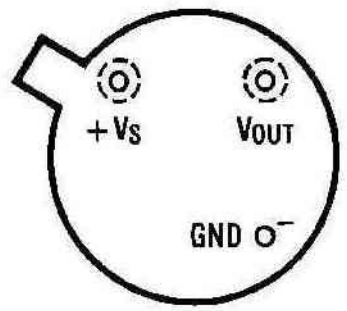
## Principle of LM35/LM34

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- ❑ These sensors are based on temperature sensitivity of band gap voltage of silicon junction.
- ❑ Band gap (or energy gap) is the energy range in a solid where no free electron states can exist.
- ❑ Band gap in a semiconductor will decrease as its temperature is raised.
- ❑ This property (temperature sensitivity) of semiconductors forms the basis of all silicon temperature sensors.

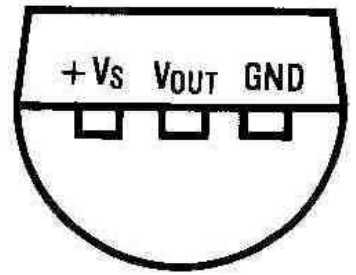
# Packages and Pins of LM35

**TO-46  
Metal Can Package\***



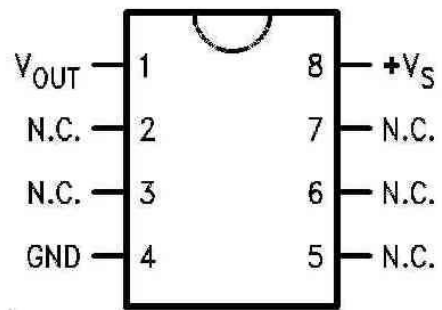
**BOTTOM VIEW**

**TO-92  
Plastic Package**

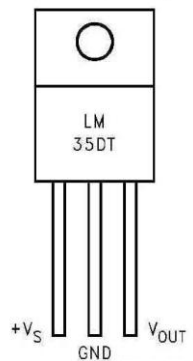


**BOTTOM VIEW**

**SO-8  
Small Outline Molded Package**



**TO-220  
Plastic Package\***





# Case Study # 2

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## Smart Humidity and Temperature Sensor

**SHT7x / SHT1x**

Manufacturer: Sensirion Corporation

Website: [www.sensirion.com](http://www.sensirion.com)

## Salient Features

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- ❑ Senses relative humidity and temperature
- ❑ Single chip sensor-cum-transmitter
- ❑ Capacitive polymer sensing element for relative humidity
- ❑ Band-gap for temperature sensing
- ❑ CMOS & micromachining technologies combined
- ❑ Patented as “CMOS Sens” Technology
- ❑ Serial digital output
- ❑ Self calibration

# Devices in SHTxx Series

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## Pin-Type Package

SHT 71

SHT 75



## SMD Package

SHT 10

SHT 11

SHT 15

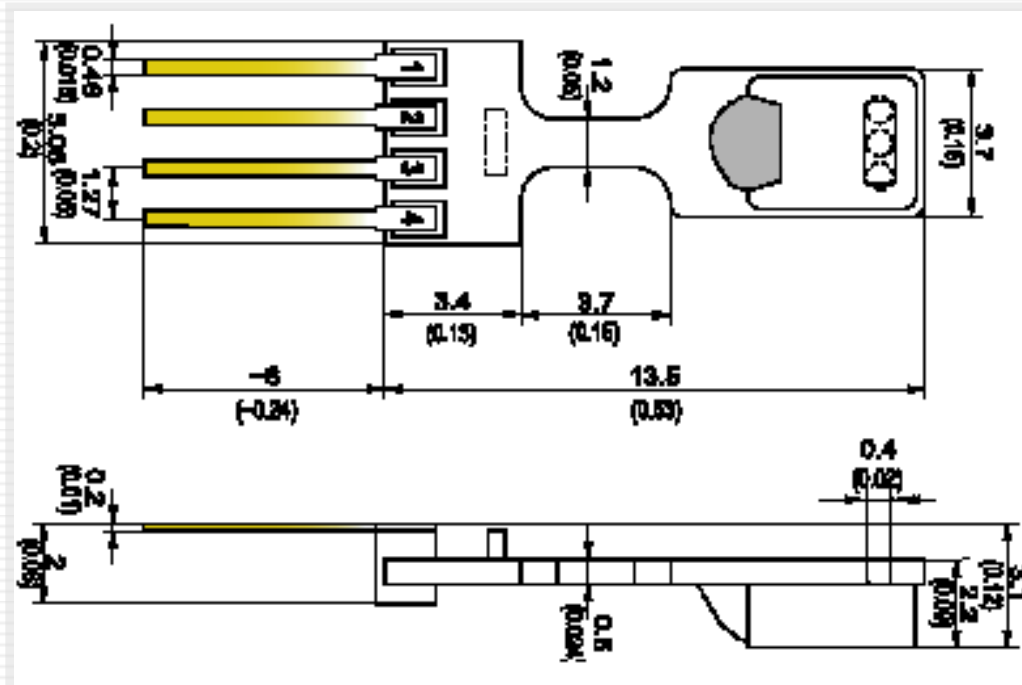


## Technical Data

Feature	SHT 71	SHT 75	SHT 10	SHT 11	SHT 15
RH Accuracy	± 3%	± 1.8%	± 4.5%	± 3%	± 2%
RH Range	0-100%			0-100%	
RH Stability	<0.5% per year		<0.5% per year		
Temp. Accuracy @ 25°C	0.4°C	± 0.3°C	±0.5°C	±0.4°C	0.3°C
Temp. Range	-40 to + 120°C		-40 to + 120°C		
<b>Power Consumption</b>	<b>30μW</b>	<b>20μW</b>	<b>30μW</b>	<b>30μW</b>	<b>30μW</b>
Response Time	4s		4s		
Package	4-Pin SIL		SMD (LCC)*		

*\*Surface mounting device (leadless chip carrier)*

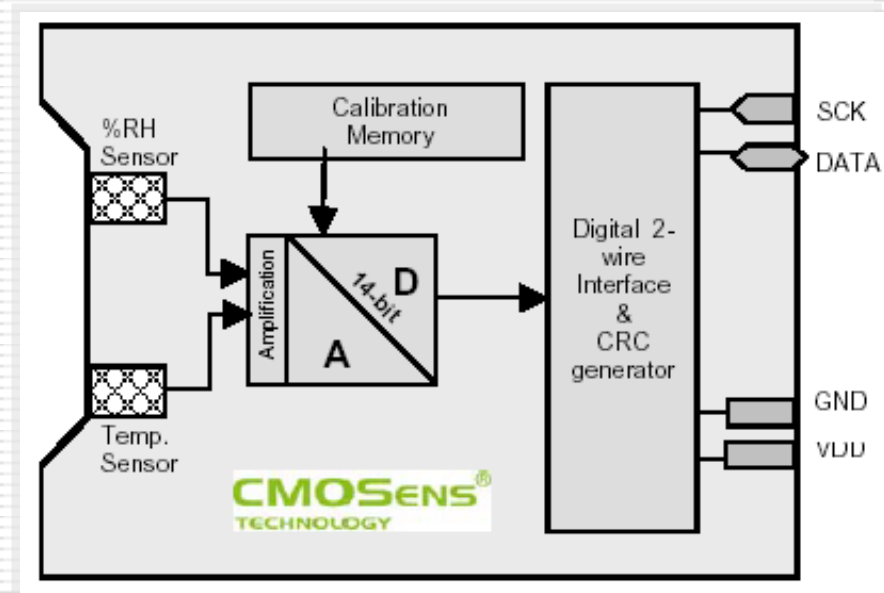
# Dimensions of SHT7x



(Source: Data sheet of SHTxx)

# Block Diagram

Pin No.	Pin Name	Description
1	SCK	Serial clock input
2	VDD	Supply 2.4 – 5.5 V
3	GND	Ground
4	DATA	Serial data bidirectional



*Serial interface of SHTxx is not compatible with I<sup>2</sup>C interfaces.*

# Case Study # 3

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## Smart Acceleration Sensor or iMEMS Accelerometer

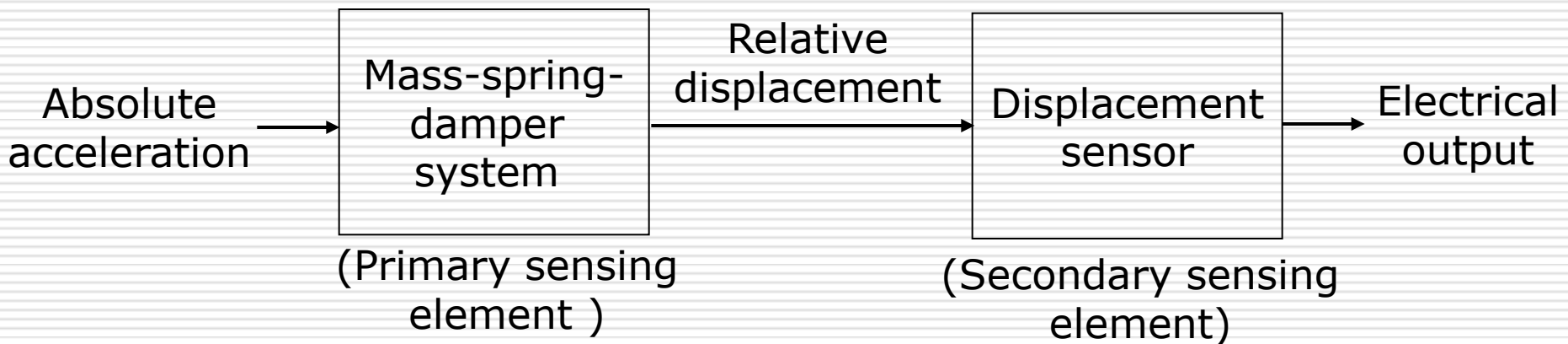
**ADXL  
150/250/210/311**

Manufacturer: Analog Devices

Website: [www.analog.com](http://www.analog.com)

# Basic Principle of Acceleration Sensors

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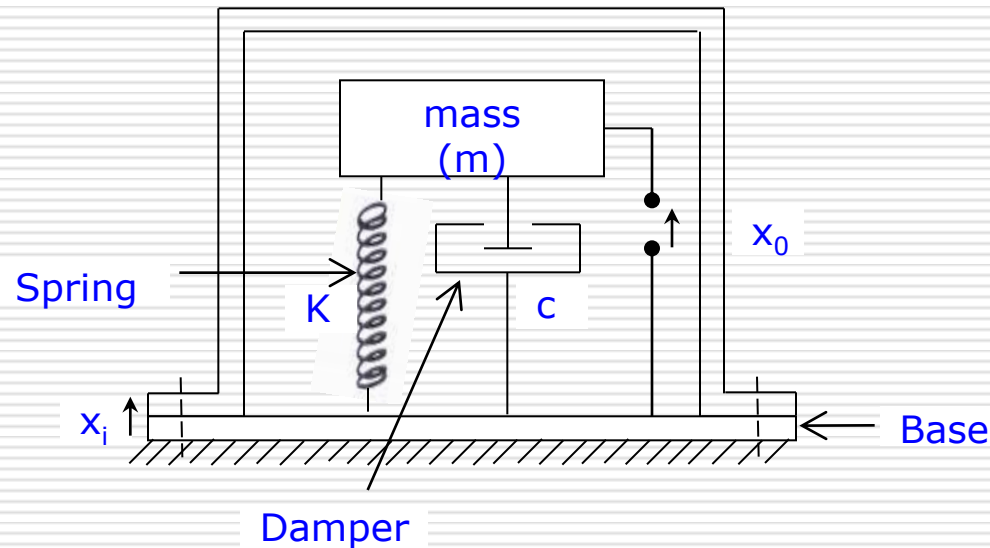


## Displacement Sensor Options

- (a) Strain gauge: Output is change in resistance
- (b) Capacitive displacement sensor: Output is change in capacitance
- (c) Piezoelectric transducer: Output is electric charge



# Mass-Spring-Damper (MSD) System



$m$  = mass in kg

$c$  = damping constant in Ns/m

$k$  = spring stiffness in N/m

# Frequency Response of MSD System

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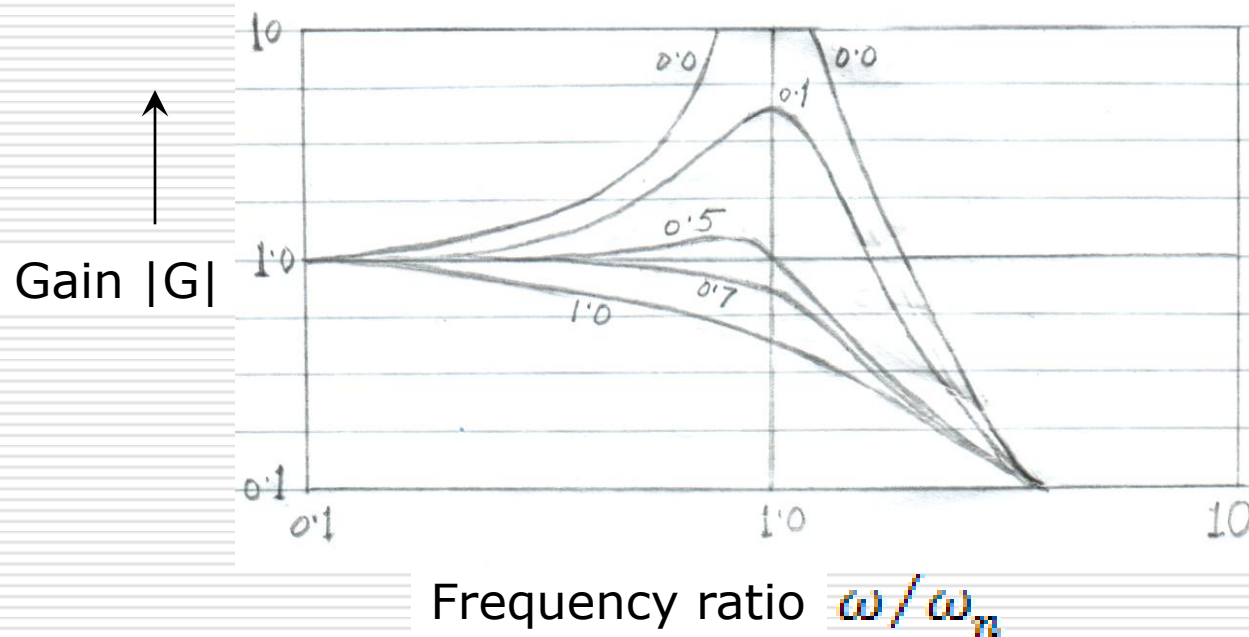
$$G(j\omega) = \frac{1/\omega_n^2}{1 + \left(j\omega/\omega_n\right)^2 + 2j\xi(\omega/\omega_n)}$$

where  $G$  is the ratio of relative displacement (output),  $x_0$   
to the absolute acceleration (input),  $x_i$ ,

$\omega_n$  is the natural frequency, and

$\xi$  is the damping ratio.

# Frequency Response Plot of MSD System



## Smart Acceleration Sensors: ADXL Series

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□ **ADXL 150: Single-axis**

14-Pin dual-in-line (DIL) package

**DC output**

□ **ADXL 250: Dual-axis**

14-Pin dual-in-line (DIL) package

**DC output**

□ **ADXL 210: Dual-axis**

8-Terminal leadless chip carrier (LLC) package

**PWM output**

□ **ADXL 311: Dual-axis**

8-Terminal leadless chip carrier (LLC) package

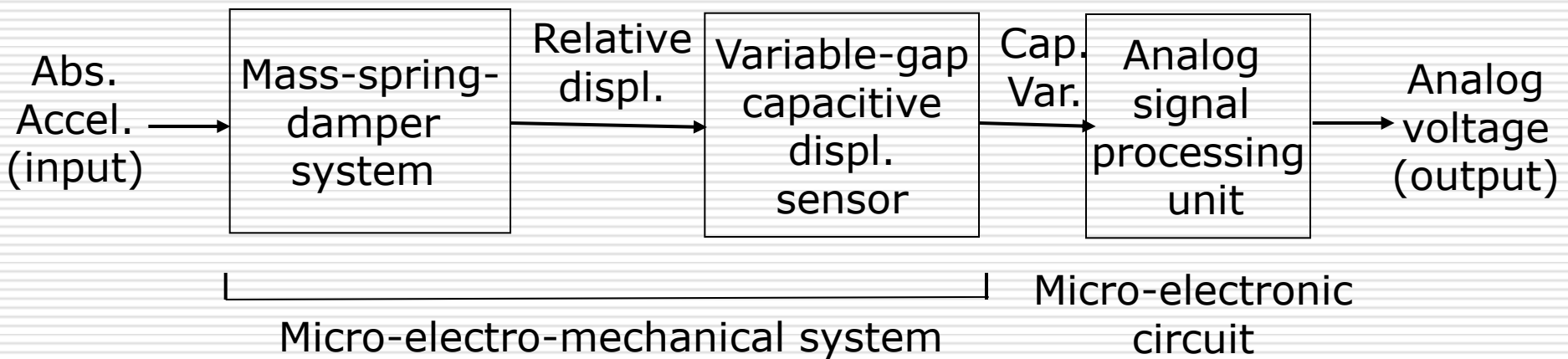
**DC output**

## Common Features of ADXL Series

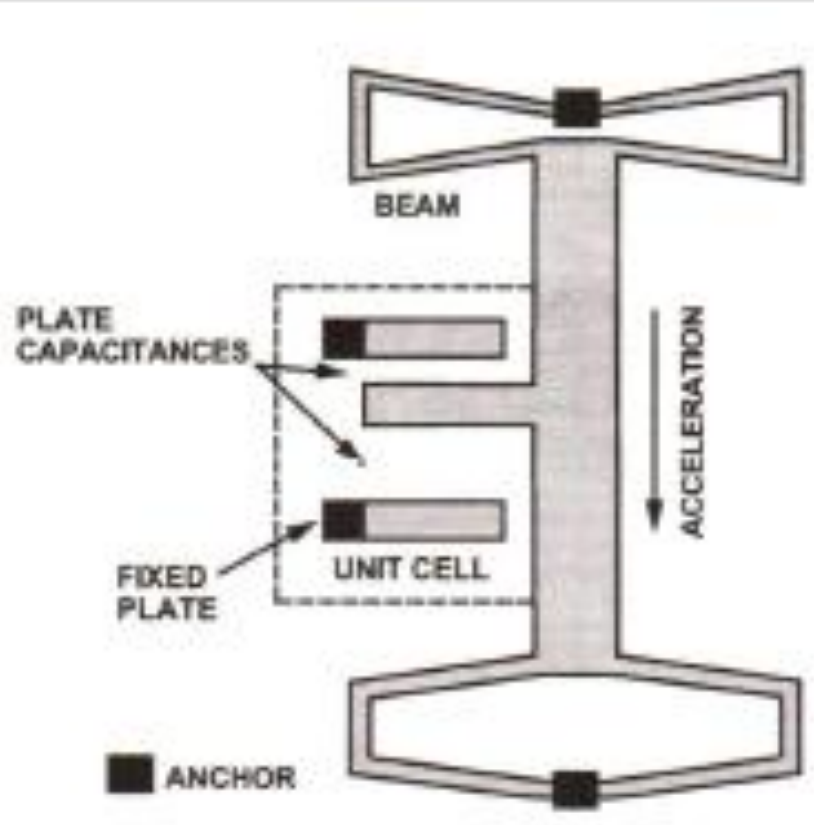
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- ❑ Can measure dynamic acceleration (vibrations) as well as static acceleration (gravity)
- ❑ Ultra-small package
- ❑ Ultra-low weight (<1 gram)
- ❑ Low power (<0.5 mA @ Vs)
- ❑ Output is ratiometric to supply voltage
- ❑ Self test feature
- ❑ 1000 g shock survival
- ❑ Sensing element fabricated using proprietary surface micromachining process.

# Block Schematic of ADXL-150

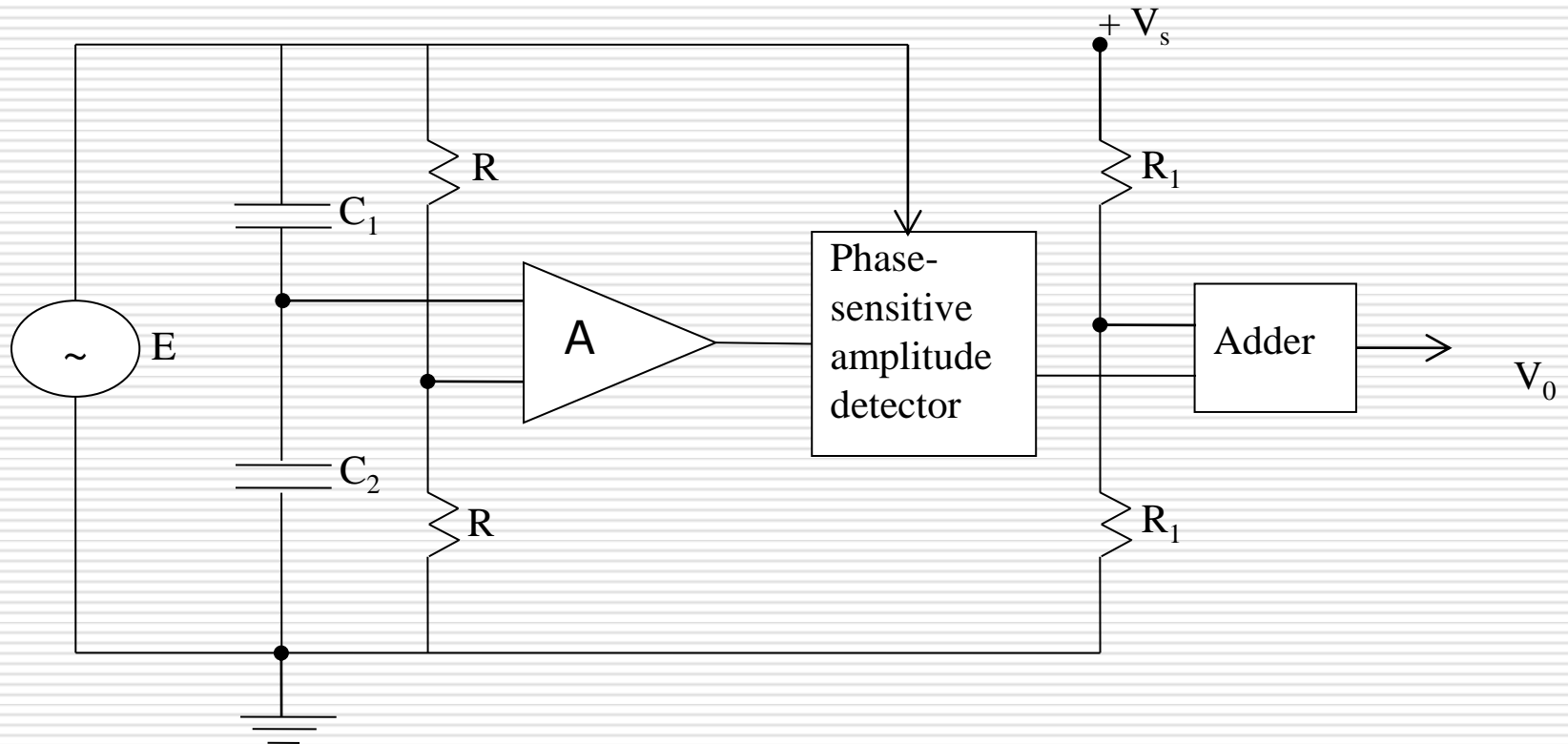


# Sensor (MEMS) of ADXL



(Source: Data sheets of ADXL-150)

# ASPU of ADXL-150



For acceleration = 0,  $C_1 = C_2 = C$

For acceleration =  $a$ ,  $C_1 = C + \Delta C$  &  $C_2 = C - \Delta C$

For acceleration =  $-a$ ,  $C_1 = C - \Delta C$  &  $C_2 = C + \Delta C$



## Output of ADXL-150

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- The output of signal processing circuit is a d.c. voltage
- It is ratiometric and given by

$$V_0 = \frac{V_s}{2} + S.a. \frac{V_s}{5}$$

- Here

$V_0$  = output voltage

$V_s$  = supply voltage (actual)

$S$  = sensitivity of the smart sensor in V/g @ 5V

$a$  = acceleration in g

- The maximum value of  $S.a. \frac{V_s}{5}$  is less than  $\pm V_s/2$ .
- Therefore, the sensor output  $V_0$  is always positive.

# Specifications of ADXL-150

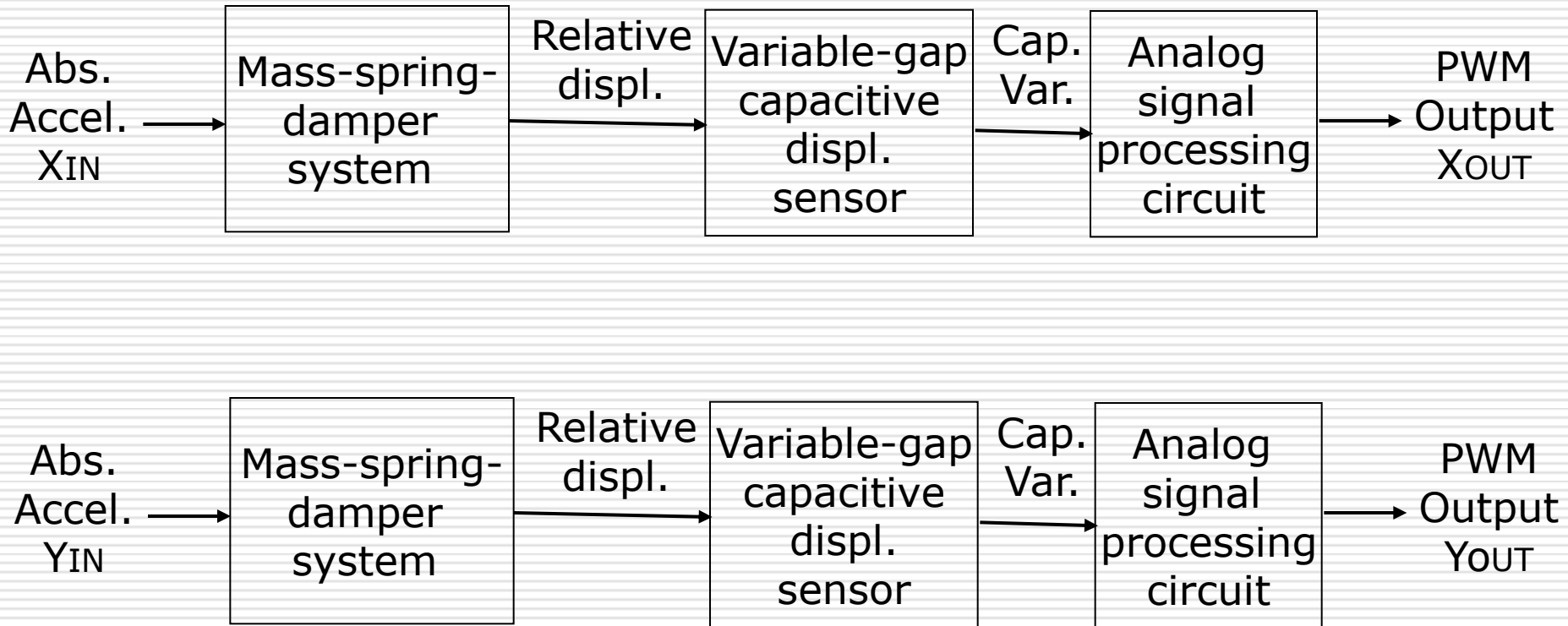
Input Range	:	$\pm 50 \text{ g}$
Power Supply ( $V_s$ )	:	4.0 V to 6.0 V
Sensitivity @ $V_s = 5\text{V}$	:	38 mV/g
Transverse Sensitivity	:	$\pm 2\%$
Zero-g offset	:	$0.5 V_s$
Output Swing	:	0.25 V to $V_s - 0.25 \text{ V}$
<b>Sensor Resonant Freq.</b>	:	<b>24 kHz</b>
<b>3dB Bandwidth</b>	:	<b>1 kHz</b>
Output change on Self Test	:	0.25 to 0.60 V
Operating Temperature	:	0 to $70^\circ\text{C}$

## Important Features of ADXL-210E

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- ❑ **Dual-axis sensor** on a single IC chip
- ❑ Ultra-small chip (5x5x2 mm)
- ❑ **PWM output**, allowing direct interface to low-cost microcontrollers
- ❑ Adjustable duty cycle period (0.5 – 1.0 ms)
- ❑ Wide operating voltage range (3V - 5.25V)

# Block Schematic of ADXL-210E



## Case Study # 4

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# Smart Pressure Sensor or Integrated Silicon Pressure Sensor

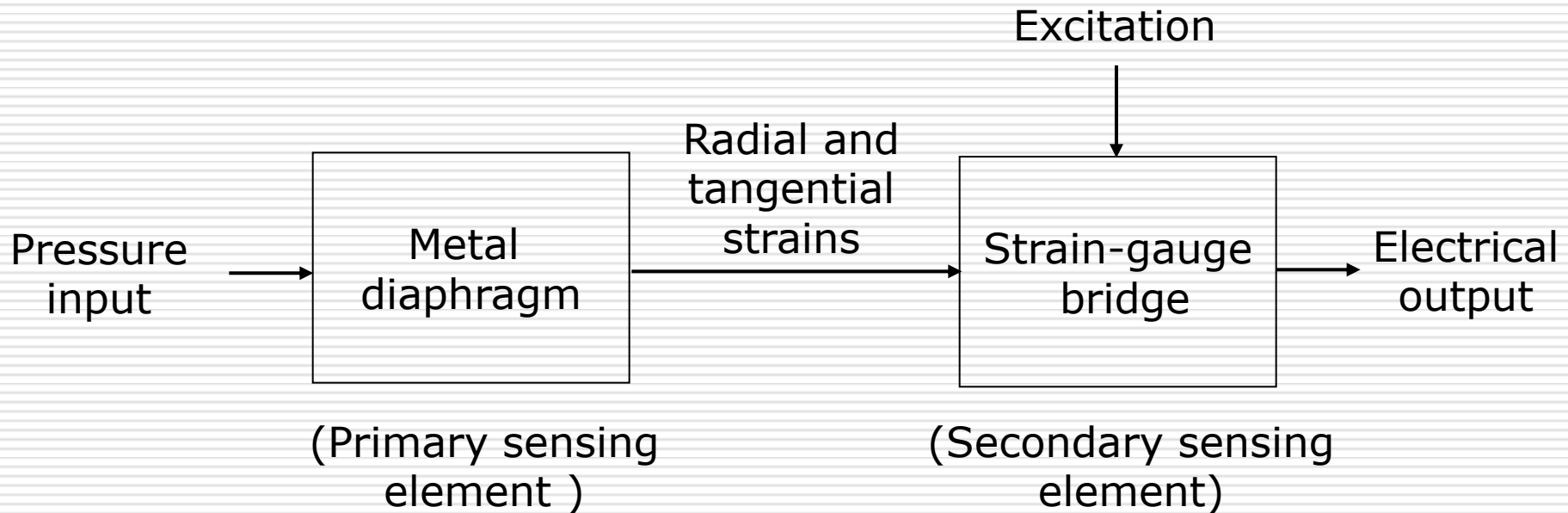
**MPX5700 Series**

Manufacturer: Freescale Semiconductor Inc.

Website: [www.freescale.com](http://www.freescale.com)

# Principle of Conventional Pressure Sensor of Diaphragm Type using Strain Gauges

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## Salient Features of MPX5700

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- ❑ Monolithic silicon pressure sensor
- ❑ Diaphragm based piezo-resistive sensor
- ❑ High-level analog output signal
- ❑ **Combines micromachining, bipolar IC and thin-film metallization techniques**
- ❑ **Available for absolute, differential and gauge pressure measurements**

## Variants of MPX5700

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### □ MPX5700A

- Smart ***absolute*** pressure sensor
- Has single pressure port

### □ MPX5700D

- Smart ***differential*** pressure sensor
- Has two pressure ports

### □ MPX5700G

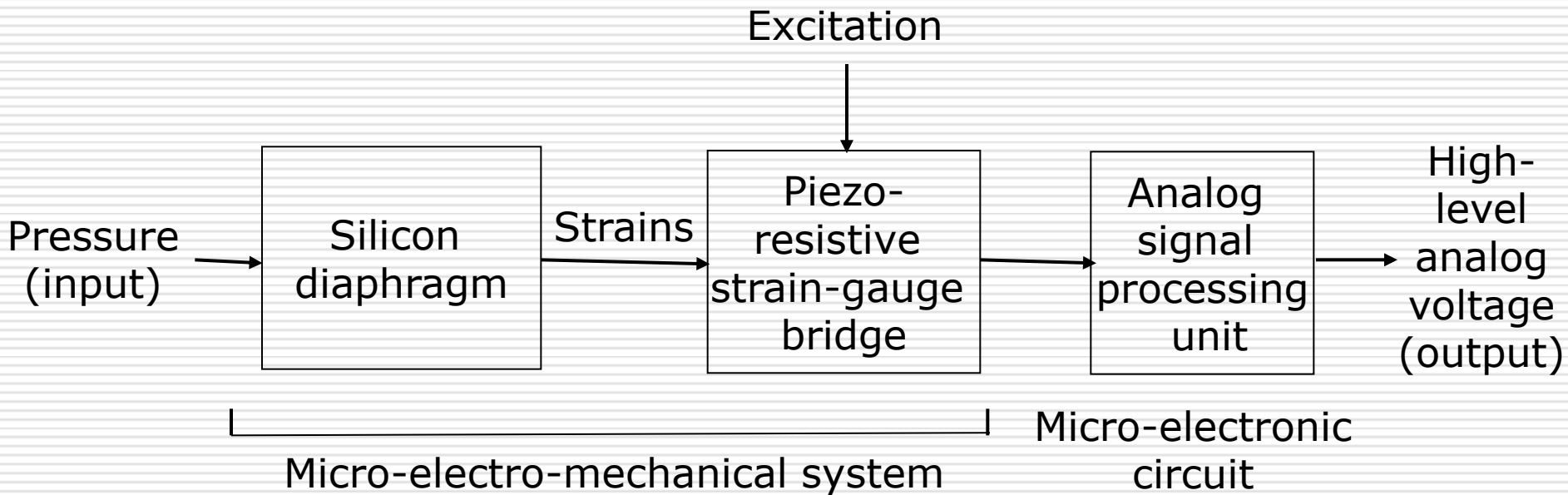
- Smart ***gauge*** pressure sensor
- Has single pressure port



# Operating Characteristics of MPX5700

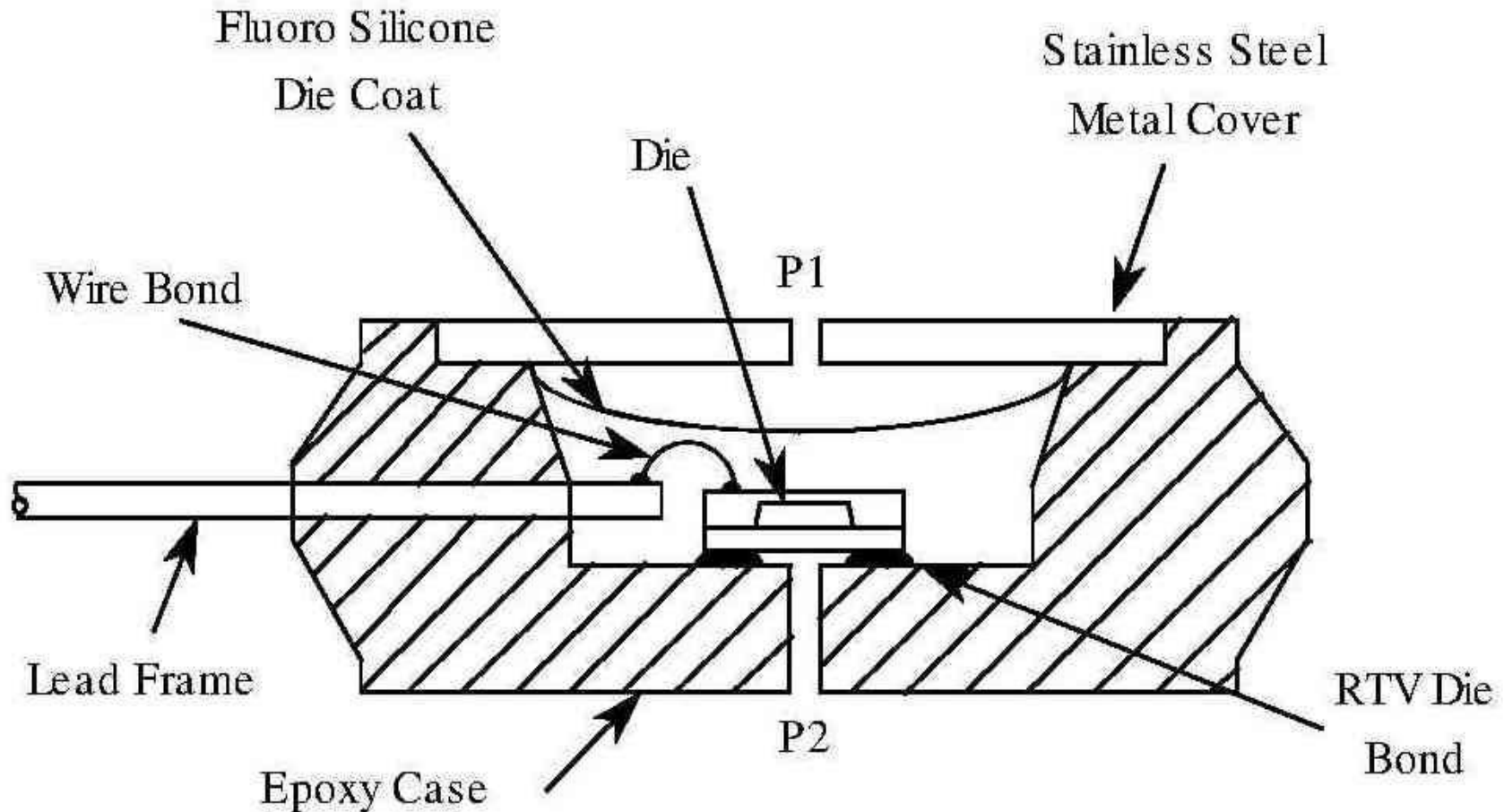
S. No.	Characteristic	Value
1	Pressure Range for Gauge/Differential sensors	0 – 700 kPa
2	Pressure Range for Absolute pressure sensors	15 – 700 kPa
3	Supply Voltage	5.0 ± 0.25V Vdc
4	Full Scale Output	4.7 Vdc
5	Accuracy	±2.5 %V <sub>FSS</sub>
6	Sensitivity	6.4 mV/kPa
7	<b>Response Time for 10% to 90% change</b>	<b>1.0 ms</b>
8	Warm-Up Time	20 ms

# Block Schematic of MPX5700





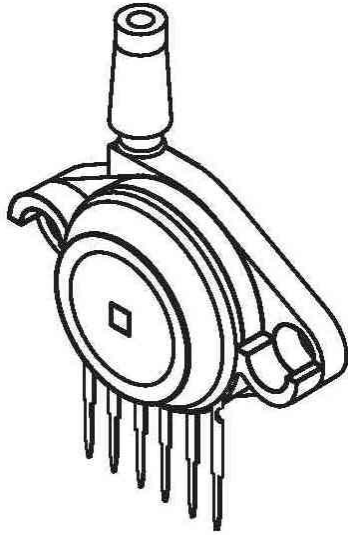
# Construction: Cross-Sectional Diagram of Absolute Pressure Sensing Element



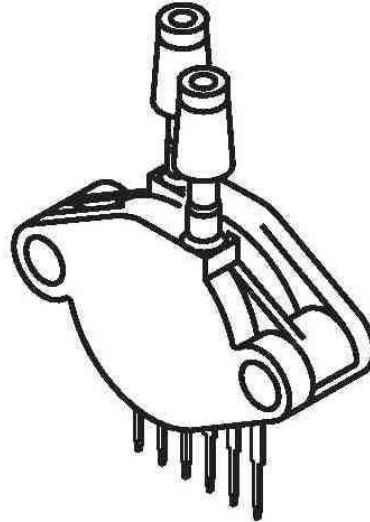
## ABSOLUTE ELEMENT

(Source: Data sheet of MPX5700)

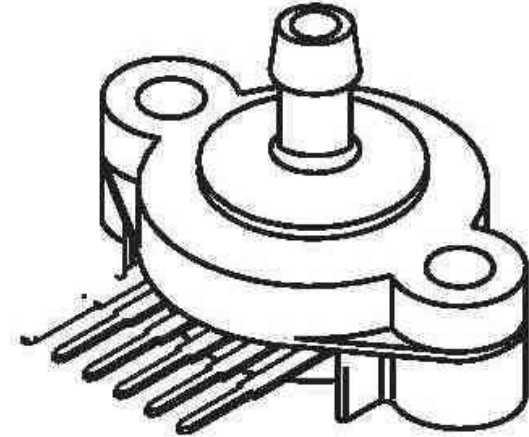
## Packages and Pins



**MPX5700AP/GP/GP1  
CASE 867B-04**



**MPX5700DP  
CASE 867C-05**



**MPX5700ASX  
CASE 867F-03**

PIN 1:  $V_{OUT}$

PIN 4:  $V_1$

PIN 2: GROUND

PIN 5:  $V_2$

PIN 3:  $V_{CC}$

PIN 6:  $V_{EX}$

(Source: Data sheet of MPX5700)

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Thank you!